Single Input Buffer

The NL17SZ16 is a single input Buffer in two tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive.

Features

- Tiny SOT–353 and SOT–553 Packages
- Source/Sink 24 mA at 3.0 Volts
- Over-Voltage Tolerant Inputs and Outputs
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Pb-Free Packages are Available

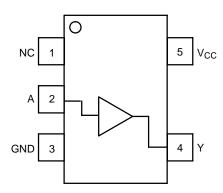


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol

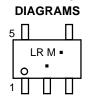


ON Semiconductor®

http://onsemi.com



SOT-353/SC70-5/SC-88A DF SUFFIX CASE 419A



MARKING



CASE 463B



LR = Device Code

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

Pin	Function
1	NC
2	IN A
3	GND
4	OUT Y
5	V _{CC}

FUNCTION TABLE

A Input	Y Output		
L	L		
Н	Н		

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Pa	rameter	Value	Unit	
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V	
VI	DC Input Voltage	Output in High or Low State (Note 2)	$-0.5 \le V_{I} \le +7.0$	V	
Vo	DC Output Voltage	V _I < GND	$-0.5 \le V_{O} \le +7.0$	V	
I _{IK}	DC Input Diode Current	V _O < GND	-50	mA	
I _{OK}	DC Output Diode Current		-50	mA	
I _{OUT}	DC Output Sink Current		±50	mA	
Icc	DC Supply Current per Supply Pin	C Supply Current per Supply Pin			
I _{GND}	DC Ground per Supply Pin		± 100	mA	
T _{STG}	Storage Temperature Range		-65 to +150	°C	
TL	Lead Temperature, 1 mm from Case for	or 10 Seconds	260	°C	
TJ	Junction Temperature Under Bias		+ 150	°C	
$\theta_{\sf JA}$	Thermal Resistance	SOT-353 SOT-553	350 360	°C/W	
P _D	Power Dissipation in Still Air at 85°C	SOT-353 SOT-553	150 180	mW	
MSL	Moisture Sensitivity		Level 1		
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in		
ESD	ESD Classification	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	Class IC Class A N/A	V	
I _{Latchup}	Latchup Performance	Above V _{CC} and Below GND at 85°C (Note 6)	±500	mA	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- Io Absolute Maximum Rating Must be Obtained.
 Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.
 Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.
- 5. Tested to JESD22-C101-A.
- 6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V _{CC}	DC Supply Voltage	Operations Only Data Retention	1.65 1.5	5.5 5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
V _{OUT}	DC Output Voltage		0	5.5	V
T _A	Operating Temperature Range		-40	+85	°C
t _r , t _f	Input Rise and Fall Time	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0 0	20 10 5	ns/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

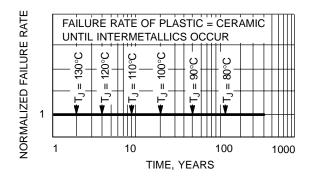


Figure 3. Failure Rate vs. Time Junction Temperature

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T	T _A = 25°C		-40°C ≤	Γ _A ≤ 85°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
V _{ОН}	High-Level Output Voltage V _{IN} = V _{IL} or V _{IH}	$I_{OH} = -100 \ \mu A$ $I_{OH} = -3 \ mA$ $I_{OH} = -8 \ mA$ $I_{OH} = -12 \ mA$ $I_{OH} = -16 \ mA$ $I_{OH} = -24 \ mA$ $I_{OH} = -32 \ mA$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V _{CC} 1.52 2.1 2.4 2.7 2.5 4.0		V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8		V
V _{OL}	Low-Level Output Voltage V _{IN} = V _{IH} or V _{OH}	$\begin{split} I_{OL} &= 100 \; \mu A \\ I_{OL} &= 4 \; mA \\ I_{OL} &= 8 \; mA \\ I_{OL} &= 12 \; mA \\ I_{OL} &= 16 \; mA \\ I_{OL} &= 24 \; mA \\ I_{OL} &= 32 \; mA \end{split}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.0 0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I _{IN}	Input Leakage Current	$V_{IN} = V_{CC}$ or GND	0 to 5.5			± 0.1		±1.0	μΑ
I _{OFF}	Power Off–Output Leakage Current	V _{OUT} = 5.5 V	0			1		10	μΑ
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1		10	μΑ

AC ELECTRICAL CHARACTERISTICS $t_R = t_F = 3.0 \text{ ns}$

			V_{CC} $T_A = 25^{\circ}C$		T _A = 25°C		-40°C ≤ 7	Γ _A ≤ 85°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
t _{PLH} t _{PHL}	Propagation Delay (Figure 4 and 5)	$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	1.65 1.8 2.5 ± 0.2 3.3 ± 0.3 5.0 ± 0.5	2.0 2.0 0.8 0.5 0.5	5.3 4.4 2.9 2.1 1.8	11.4 9.5 6.5 4.5 3.9	2.0 2.0 0.8 0.5 0.5	12 10 7.0 4.7 4.1	ns
		$R_L = 500 \Omega, C_L = 50 pF$	3.3 ± 0.3 5.0 ± 0.5	1.5 0.8	2.9 2.4	5.0 4.3	1.5 0.8	5.2 4.5	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	>4	pF
C _{PD}	Power Dissipation Capacitance (Note 7)	10 MHz, $V_{CC} = 3.3 \text{ V}$, $V_{I} = 0 \text{ V}$ or V_{CC} 10 MHz, $V_{CC} = 5.5 \text{ V}$, $V_{I} = 0 \text{ V}$ or V_{CC}	25 30	pF

^{7.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

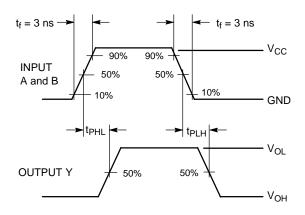
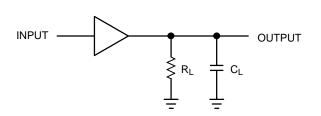


Figure 4. Switching Waveform



A 1–MHz square input wave is recommended for propagation delay tests.

Figure 5. Test Circuit

ORDERING INFORMATION

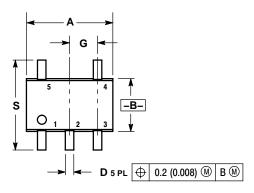
Device	Package	Shipping [†]
NL17SZ16DFT2	SOT-353/SC70-5/SC-88A	
NL17SZ16DFT2G	SOT-353/SC70-5/SC-88A (Pb-Free)	3000/Tape & Reel
NL17SZ16XV5T2	SOT-553*	4000/Topo & Bool
NL17SZ16XV5T2G	SOT-553*	4000/Tape & Reel

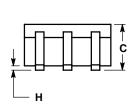
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

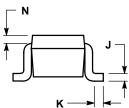
^{*}All Devices in Package SOT553 are Inherently Pb-Free.

PACKAGE DIMENSIONS

SC-88A, SOT-353, SC-70 CASE 419A-02 **ISSUE J**





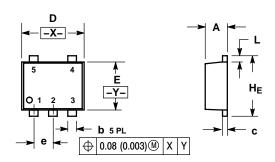


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS
DIM	MIN MAX		MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65 BSC	
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20	REF
S	0.079	0.087	2.00	2.20

PACKAGE DIMENSIONS

SOT-553, 5 LEAD CASE 463B-01 ISSUE B

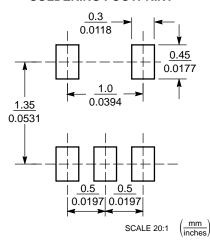


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD

THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL

	MILLIMETERS				INCHES		
DIM	MIN	NOM	MAX	MIN	MOM	MAX	
Α	0.50	0.55	0.60	0.020	0.022	0.024	
b	0.17	0.22	0.27	0.007	0.009	0.011	
С	0.08	0.13	0.18	0.003	0.005	0.007	
D	1.50	1.60	1.70	0.059	0.063	0.067	
Е	1.10	1.20	1.30	0.043	0.047	0.051	
е	0.50 BSC			0.020 BSC			
L	0.10	0.20	0.30	0.004	0.008	0.012	
HE	1.50	1.60	1.70	0.059	0.063	0.067	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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